TOSHIBA Photocoupler GaAlAs IRed & Photo-IC

# **TLP651**

Digital Logic Ground Isolation
Line Receiver
Microprocessor System Interfaces
Switching Power Supply Feedback Control
Analog Signal Isolation

The TOSHIBA TLP651 consists of a GaAlAs high–output light emitting diode and a high speed detector of one chip photo diode–transistor. This unit is 8–lead DIP.

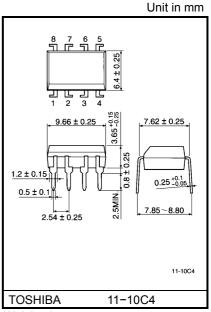
TLP651 has internal base connection. This base pin should be used for analog application or enable operation. If base pin is open, output signal will be noisy by environmental condition. For this case, TLP650 is suitable.

- Isolation voltage: 5000V<sub>rms</sub> (min.)
- Switching speed: tpHL = 0.3µs (typ.)

 $t_{pLH} = 0.5\mu s$  (typ.) (R<sub>L</sub> = 1.9k $\Omega$ )

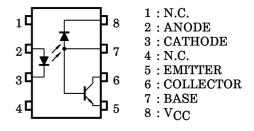
- TTL compatible
- UL recognized: UL1577, file no. E67349
- BSI approved: BS EN60065: 1994

Certiticate no. 7613 BS EN60950: 1992 Certiticate no. 7614

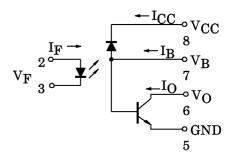


Weight: 0.54g

### Pin Configuration (top view)



#### **Schematic**



### **Maximum Ratings (Ta = 25°C)**

	Characteristic		Symbol	Rating	Unit
	Forward current	(Note 1)	l <sub>F</sub>	25	mA
	Pulse forward current	(Note 2)	I <sub>FP</sub>	50	mA
LED	Peak transient forward current	(Note 3)	I <sub>FPT</sub>	1	Α
	Reverse voltage		V <sub>R</sub>	5	V
	Diode power dissipation	(Note 4)	$P_{D}$	45	mW
	Output current		IO	8	mA
	Peak output current		I <sub>OP</sub>	16	mA
Detector	Output voltage		Vo	-0.5~15	V
	Supply voltage		V <sub>CC</sub>	-0.5~15	V
Ď	Base current		Ι <sub>Β</sub>	5	mA
	Emitter-base reverse voltage		V <sub>EB</sub>	5	V
	Output power dissipation	(Note 5)	Po	100	mW
Оре	Operating temperature range		T <sub>opr</sub>	<b>−55~100</b>	°C
Stor	rage temperature range		T <sub>stg</sub>	-55~125	°C
Lea	d solder temperature (10s)	(Note 6)	T <sub>sol</sub>	260	°C
Isola (AC	ation voltage , 1min., R.H.≤ 60%)	(Note 7)	BVS	5000	V <sub>rms</sub>

(Note 1) Derate 0.8mA above 70°C.

(Note 2) 50% duty cycle,1ms pulse width. Derate 1.6mA / °C above 70°C.

(Note 3) Pulse width ≤ 1µs, 300pps.

(Note 4) Derate 0.9mW / °C above 70°C.

(Note 5) Derate 2mW / °C above 70°C.

(Note 6) Soldering portion of lead: Up to 2mm from the body of the device.

(Note 7) Device considered a two terminal device: Pins 1, 2, 3 and 4 shorted together and pins 5, 6, 7 and 8 shorted together.

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# Electrical Characteristics (Ta = 25°C)

Characteristic		Symbol	Test Condition			Min.	Тур.	Max.	Unit
	Forward voltage	V <sub>F</sub>	I <sub>F</sub> = 16mA			_	1.65	1.85	V
CED	Forward voltage temperature coefficient	ΔV <sub>F</sub> / ΔTa	I <sub>F</sub> = 16mA	_	-2	_	mV / °C		
	Reverse current	I <sub>R</sub>	V <sub>R</sub> = 5V	_	-	10	μΑ		
	Capacitance between terminal	C <sub>T</sub>	V <sub>F</sub> = 0, f = 1MHz			_	45	_	pF
	High level output current	I <sub>OH (1)</sub>	$I_F = 0mA, V_{CC} = V_O = 5.5V$			-	3	500	nA
Detector		I <sub>OH (2)</sub>	$I_F = 0mA$ , $V_{CC} = 0$		1	5	μΑ		
		Іон	I <sub>F</sub> = 0mA, V <sub>CC</sub> = 1 Ta = 70°C	1	_	250	μΑ		
	High level supply voltage	Icch	I <sub>F</sub> = 0mA, V <sub>CC</sub> =	_	0.01	1	μΑ		
	Current transfer ratio	I <sub>O</sub> / I <sub>F</sub>		Ta = 25°C		10	30	_	
			$I_F = 16mA$ $V_{CC} = 4.5V$ $V_O = 0.4V$		Rank: O	19	30	_	%
				Ta = 0~	-70°C	5	1	_	/6
g					Rank: O	15	ı	ı	
Coupled	Low level output voltage	V <sub>OL</sub>	I <sub>F</sub> = 16mA, V <sub>CC</sub> = I <sub>O</sub> = 1.1mA (Rank 0: I <sub>O</sub> = 2.4	-	_	0.4	V		
	Isolation resistance	R <sub>S</sub>	R.H.≤ 60%, V <sub>S</sub> =	5×10 <sup>10</sup>	10 <sup>14</sup>	_	Ω		
	Capacitance between input to output	CS	V <sub>S</sub> = 0, f = 1MHz (Note 7)			_	0.8	_	pF

# Switching Characteristics (Ta = 25°C, $V_{CC} = 5V$ )

Characteristic		Symbol	Test Cir– cuit	Test Condition		Min.	Тур.	Max.	Unit
Propagation delay time		<b>t</b>		$I_F = 0 \rightarrow 16 \text{mA}, V_{CC} = 5 \text{V},$		_	0.2	0.8	μs
(H→L)		t <sub>pHL</sub>	1	R <sub>L</sub> =4.1kΩ	Rank O: R <sub>L</sub> =1.9kΩ	_	<b>—</b> 0.3 0.8		μδ
Propagation delay time		t <sub>pLH</sub>	] '	I <sub>F</sub> = 16→ 0mA, V <sub>CC</sub> = 5V,		_	1.0	2.0	116
(L→H)				R <sub>L</sub> =4.1kΩ	Rank O: R <sub>L</sub> =1.9kΩ	_	0.5	1.2	μs
Common mode transient immunity at logic high output	(Note 8)	C <sub>MH</sub>	2	$I_F$ = 0mA, $V_{CM}$ = 200 $V_{p-p}$ $R_L$ = 4.1kΩ (Rank O: $R_L$ = 1.9kΩ)		ı	400	ı	V / µs
Common mode transient immunity at logic low output	(Note 8)	C <sub>ML</sub>	2	$I_F$ =16mA, $V_{CM}$ = 200 $V_{p-p}$ R <sub>L</sub> = 4.1kΩ (Rank O: R <sub>L</sub> = 1.9kΩ)		_	-1000	_	V / µs

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200V

0V

5V

2V 0.8V

 $\cdot v_{OL}$ 

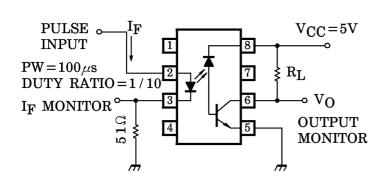
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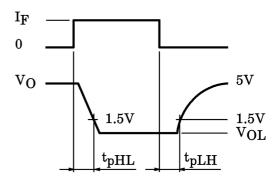
(Note 8) CM<sub>L</sub> is the maximum rate of fall of the common mode voltage that can be sustained with the output voltage in the logic low state ( $V_O < 0.8V$ ).

 $CM_H$  is the maximum rate of rise of the common mode voltage that can be sustained with the output voltage in the logic high state ( $V_O > 2.0V$ ).

(Note 9) Maximum electrostatic discharge voltage for any pins: 100V (C = 200pF, R = 0).

### **Test Circuit 1: Switching Time Test Circuit**



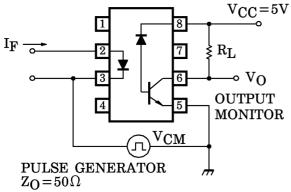


90%

10%

 $t_f$ 

### **Test Circuit 2: Common Mode Noise Immunity Test Circuit**

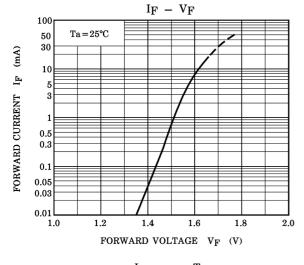


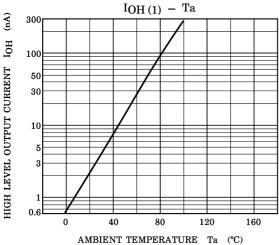
$$V_{O}$$
 $(I_{F}=0\text{mA})$ 
 $V_{O}$ 
 $(I_{F}=16\text{mA})$ 

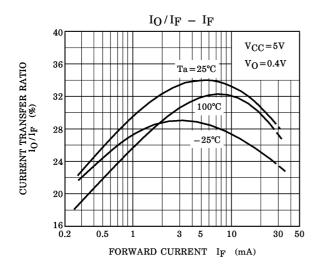
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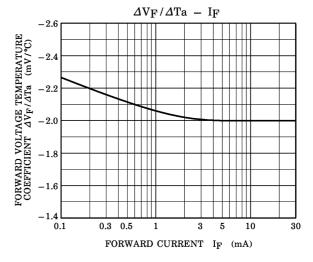
 $V_{CM}$ 

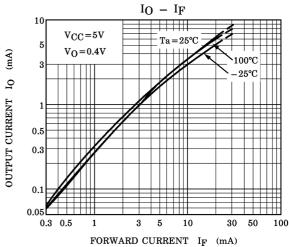
$$\mathrm{CM_{H}} = \frac{160\,\mathrm{(V)}}{\mathrm{t_r}\,(\mu\mathrm{s})}$$
 ,  $\mathrm{CM_{L}} = \frac{160\,\mathrm{(V)}}{\mathrm{t_f}\,(\mu\mathrm{s})}$ 

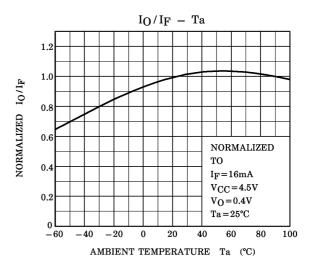


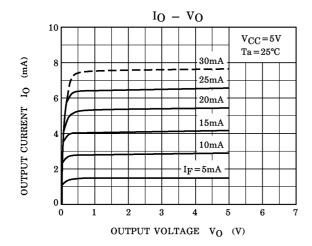


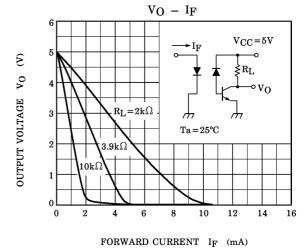


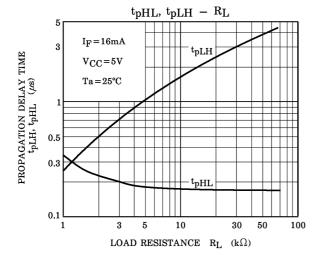












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